FAIRCHILD SEMICONDUCTOR®

October 2011

FAN7171_F085
High-Current High-Side Gate Drive IC

Features

- Floating Channel for Bootstrap Operation to +600V
- 4A/4A Sourcing/Sinking Current Driving Capability
- Common-Mode dv/dt Noise Canceling Circuit
- 3.3V and 5V Input Logic Compatible
- Output In-phase with Input Signal
- Under- Voltage Lockout for V_{BS}
- 25V Shunt Regulator on V_{DD} and V_{BS}
- 8-Lead Small Outline Package (SOP)
- Qualified to AEC Q100

Applications

- High-Speed Gate Driver
- High-Power Buck Converter
- Motor Drive Inverter

Description

The FAN7171_F085 is a monolithic high-side gate drive IC, which can drive high-speed MOSFETs and IGBTs that operate up to +600V. It has a buffered output stage with all NMOS transistors designed for high pulse current driving capability and minimum cross-conduction.

Fairchild's high-voltage process and common-mode noise canceling techniques provide stable operation of the high-side driver under high dv/dt noise circumstances. An advanced level-shift circuit offers high-side gate driver operation up to V_S=-9.8V (typical) for V_{BS}=15V.

The UVLO circuit prevents malfunction when V_{BS} is lower than the specified threshold voltage.

The high-current and low-output voltage drop feature makes this device suitable for sustaine switch driver and energy recovery switch driver in the Plasma Display Panel application, motor drive inverter, switching power supply, and high-power DC-DC converter applications.

8-SOP

Ordering Information

Part Number	Package	Operating Temperature Range	Eco Status	Packing Method
FAN7171M(1)	8-SOP	-40°C ~ 125°C	RoHS	Tube
FAN7171MX(1)				Tape & Reel

Note:
1. These devices passed wave soldering test by JESD22A-111.

For Fairchild's definition of "green" Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

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Typical Application Diagrams

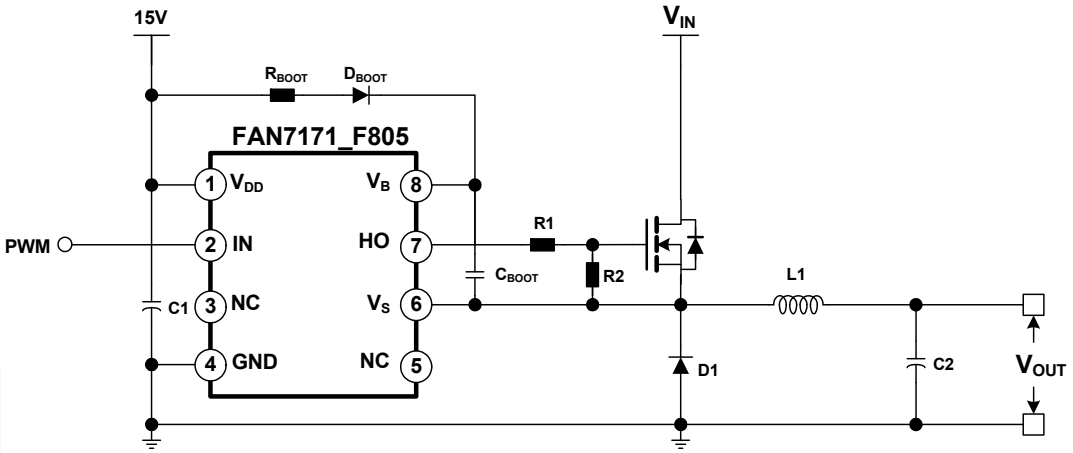

Figure 1. Application Circuit for Step-Down (Buck) DC-DC Converter

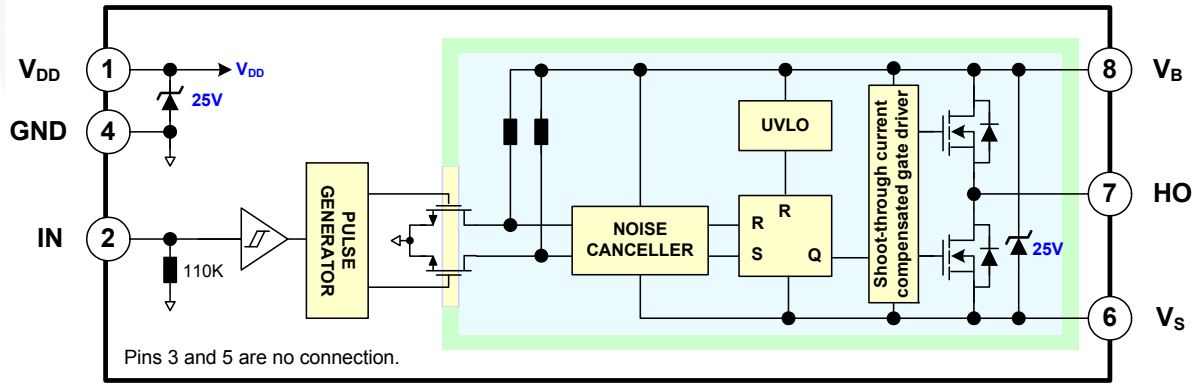

Figure 2. Functional Block Diagram

Pin Configuration

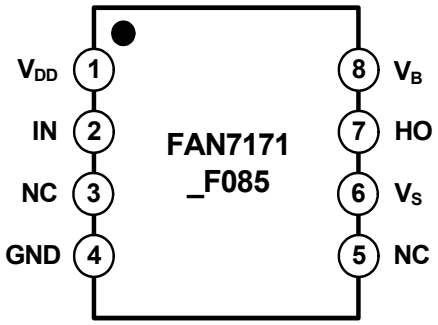

Figure 3. Pin Assignments(Top View)

Pin Definitions

Pin #	Name	Description
1	V_{DD}	Supply Voltage
2	IN	Logic Input for High-Side Gate Driver Output
3	NC	No Connection
4	GND	Ground
5	NC	No Connection
6	V_S	High-Voltage Floating Supply Return
7	HO	High-Side Driver Output
8	V_B	High-Side Floating Supply

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Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. -40°C<=T_A <=125°C unless otherwise specified.

Symbol	Characteristics	Min.	Max.	Unit
V_S	High-Side Floating Offset Voltage	V_B-V_{SHUNT}	V_B+0.3	V
V_B	High-Side Floating Supply Voltage(2)	-0.3	625.0	V
V_{HO}	High-Side Floating Output Voltage	V_S-0.3	V_B+0.3	V
V_{DD}	Low-Side and Logic Supply Voltage(2)	-0.3	V_{SHUNT}	V
V_{IN}	Logic Input Voltage	-0.3	V_{DD}+0.3	V
dV_S/dt	Allowable Offset Voltage Slew Rate		± 50	V/ns
P_D	Power Dissipation(3, 4, 5)		0.625	W
θ_{JA}	Thermal Resistance		200	°C/W
T_J	Junction Temperature	-55	150	°C
T_{STG}	Storage Temperature	-55	150	°C
T_A	Operating Ambient Temperature	-40	125	°C
V_{ESD}	Human Body Model(HBM)		1500	V
V_{CDM}	Charge Device Model		500	V

Notes:

1) This IC contains a shunt regulator on VDD and VBS with a normal breakdown voltage of 25V. Please note that this supply pin should not be driven by a low-impedance voltage source greater than the VSHUNT specified in the Electrical Characteristics section

2) Mounted on 76.2 x 114.3 x 1.6mm PCB (FR-4 glass epoxy material).

3) Refer to the following standards:
JESD51-2: Integral circuits thermal test method environmental conditions, natural convection, and
JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages.

4 Do not exceed power dissipation (P_D) under any circumstances.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{BS}	High-Side Floating Supply Voltage	V_S+10	V_S+20	V
V_S	High-Side Floating Supply Offset Voltage(DC)	6-V_{DD}	600	V
V_S	High-Side Floating Supply Offset Voltage(Transient)	-15(~170) -7(~400)	600	V
V_{HO}	High-Side Output Voltage	V_S	V_B	V
V_{IN}	Logic Input Voltage	GND	V_{DD}	V
V_{DD}	Supply Voltage	10	20	V

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Electrical Characteristics

$V_{BIAS}(V_{DD}, V_{BS})$=15.0V, -40°C<=T_A <= 125°C, unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to GND. The V_O and I_O parameters are relative to V_S and are applicable to the respective output HO.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
POWER SUPPLY SECTION						
I_{QDD}	Quiescent V_{DD} Supply Current	V_{IN}=0V or 5V		25	70	µA
I_{PDD}	Operating V_{DD} Supply Current	f_{IN}=20KHz, No Load		35	100	µA
BOOTSTRAPPED SUPPLY SECTION						
V_{BSUV+}	V_{BS} Supply Under-Voltage Positive Going Threshold Voltage	V_{BS}=Sweep	8.2	9.2	10.2	V
V_{BSUV-}	V_{BS} Supply Under-Voltage Negative Going Threshold Voltage	V_{BS}=Sweep	7.5	8.5	9.5	V
V_{BSHYS}	V_{BS} Supply Under-Voltage Lockout Hysteresis Voltage	V_{BS}=Sweep		0.6		V
I_{LK}	Offset Supply Leakage Current	V_B=V_S=600V			50	µA
I_{QBS}	Quiescent V_{BS} Supply Current	V_{IN}=0V or 5V		60	120	µA
I_{PBS}	Operating V_{BS} Supply Current	C_{LOAD}=1nF, f_{IN}=20KHz, rms value		0.73	2.8	mA
SHUNT REGULATOR SECTION						
V_{SHUNT}	V_{DD} and V_{BS} Shunt Regulator Clamping Voltage	I_{SHUNT}=5mA	23	25		V
INPUT LOGIC SECTION(IN)						
V_{IH}	Logic “1” Input Voltage		2.5			V
V_{IL}	Logic “0” Input Voltage				0.8	V
I_{IN+}	Logic Input High Bias Current	V_{IN}=5V		45	125	µA
I_{IN-}	Logic Input Low Bias Current	V_{IN}=0V			2	µA
R_{IN}	Input Pull-down Resistance		40	110		KΩ
GATE DRIVER OUTPUT SECTION(HO)						
V_{OH}	High Level Output Voltage (V_{BIAS} - V_O)	No Load			1.5	V
V_{OL}	Low Level Output Voltage	No Load			35	mV
I_{O+}	Output High, Short-Circuit Pulsed Current(5)	V_{HO}=0V, V_{IN}=5V, PW ≤10µs	3.0	4.0		A
I_{O-}	Output Low, Short-Circuit Pulsed Current(5)	V_{HO}=15V,V_{IN}=0V, PW ≤10µs	3.0	4.0		A
V_S	Allowable Negative V_S pin Voltage for IN Signal Propagation to HO			-9.8	-7.0	V

Note:

5 These parameters guaranteed by design.

Dynamic Electrical Characteristics

$V_{BIAS}(V_{DD,}V_{BS})$=15V, V_S=GND=0V, C_L=1000pF, and-40°C<= T_A <=125°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
t_{on}	Turn-on Propagation Delay Time	V_S=0V		150	210	ns
t_{off}	Turn-off Propagation Delay Time	V_S=0V		150	210	ns
t_r	Turn-on Rise Time			25	50	ns
t_f	Turn-off Fall Time			15	45	ns

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Typical Characteristics

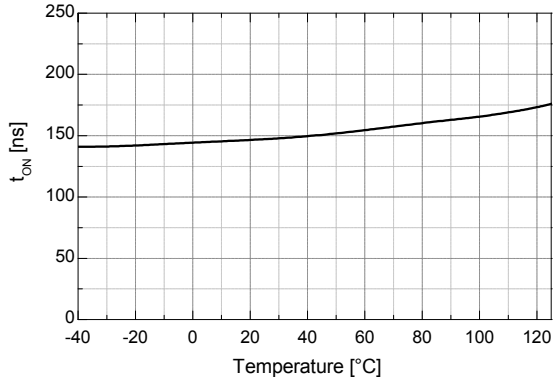

Figure 4. Turn-on Propagation Delay vs. Temperature

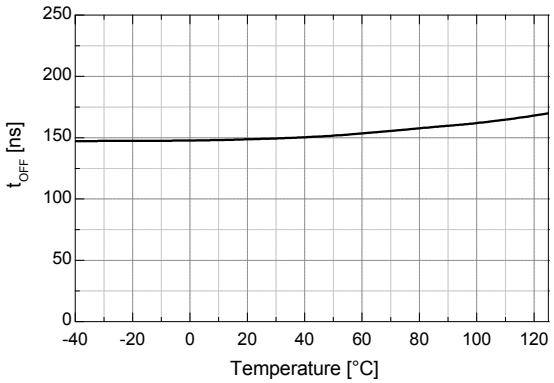

Figure 5. Turn-off Propagation Delay vs. Temperature

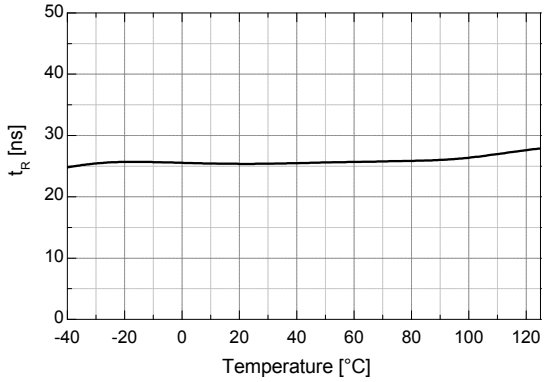

Figure 6. Turn-on Rise Time vs. Temperature

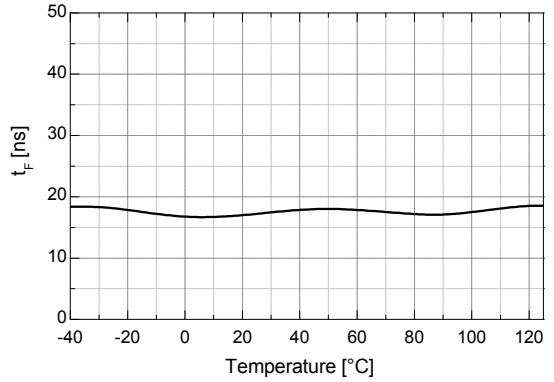

Figure 7. Turn-off Fall Time vs. Temperature

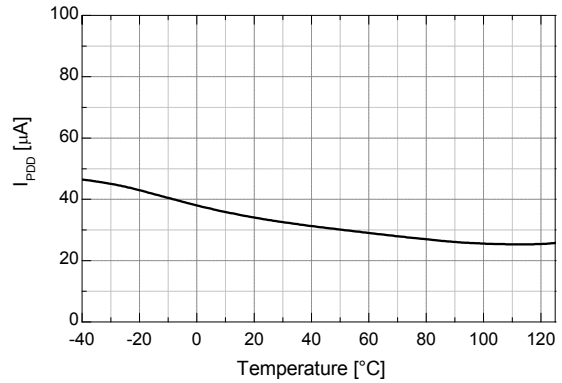

Figure 8. Operating V_{DD} Supply Current vs. Temperature

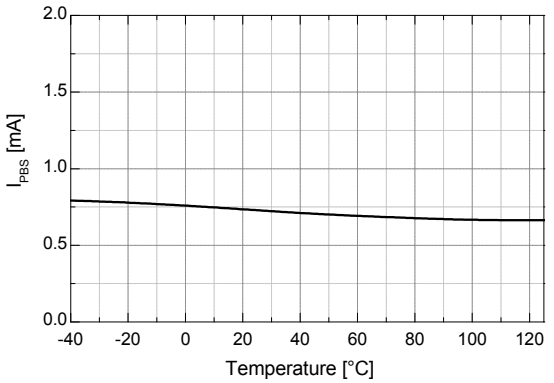

Figure 9. Operating V_{BS} Supply Current vs. Temperature

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Typical Characteristics (Continued)

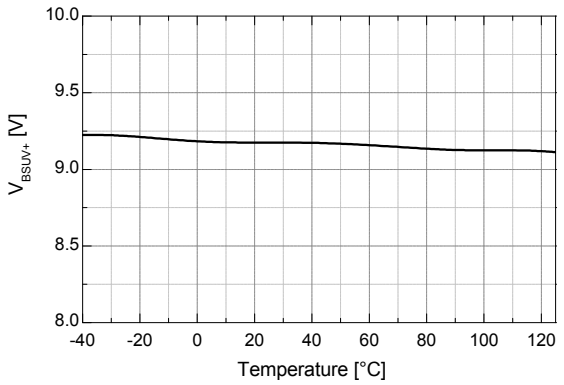

Figure 10. V_{BS} UVLO+ vs. Temperature

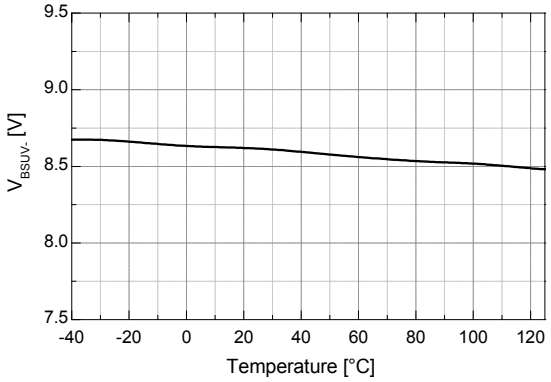

Figure 11. V_{BS} UVLO- vs. Temperature

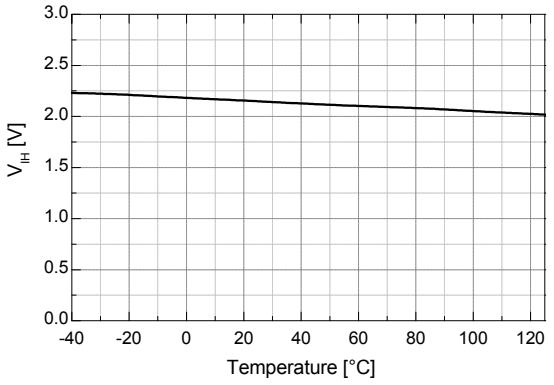

Figure 12. Logic High Input Voltage vs. Temperature

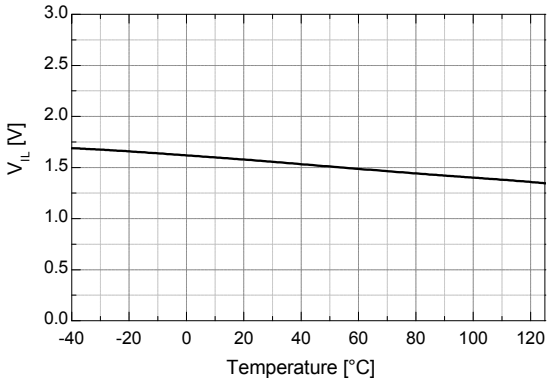

Figure 13. Logic Low Input Voltage vs. Temperature

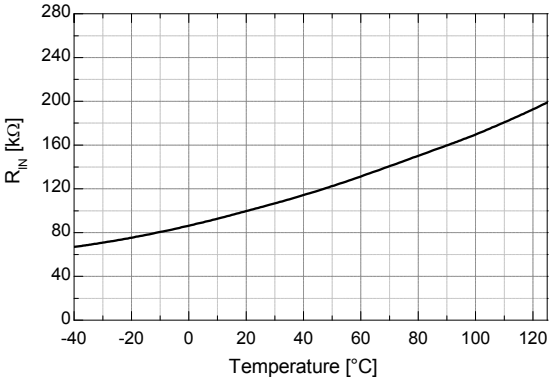

Figure 14. Input Pull-down Resistance vs.Temperature.

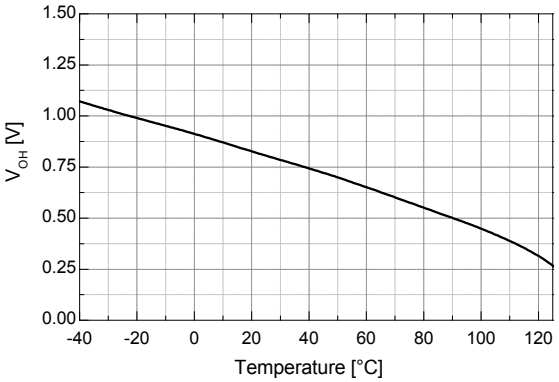

Figure 15. High-Level Output Voltage vs. Temperature

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Typical Characteristics (Continued)

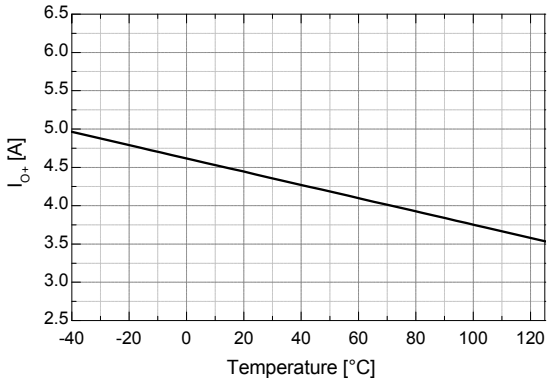

Figure 16. Output High, Short-Circuit Pulsed Current vs. Temperature

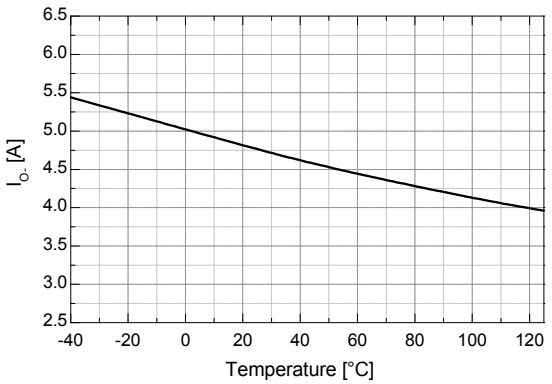

Figure 17. Output Low, Short-Circuit Pulsed Current vs. Temperature

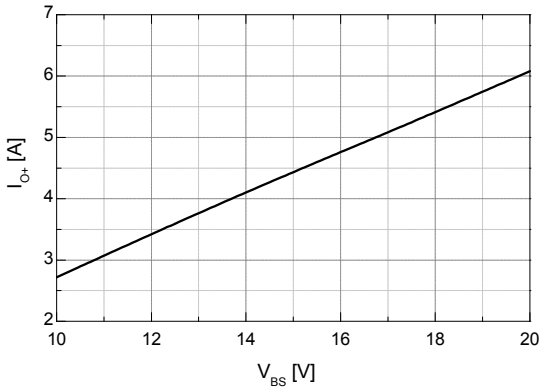

Figure 18. Output High, Short-Circuit Pulsed Current vs. Supply Voltage

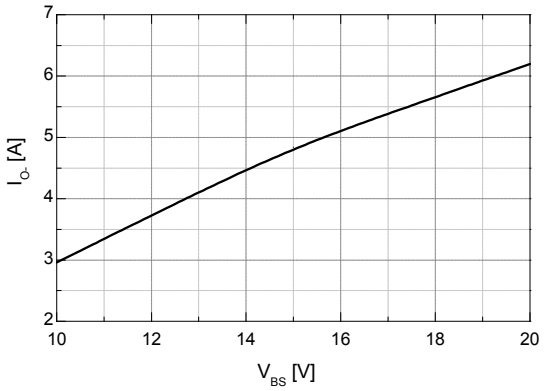

Figure 19. Output Low, Short-Circuit Pulsed Current vs. Supply Voltage

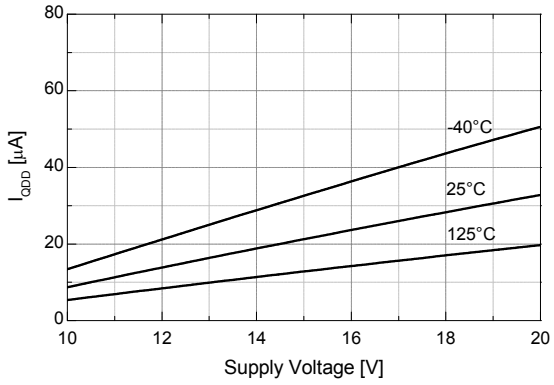

Figure 20. Quiescent V_{DD} Supply Current vs. Supply Voltage

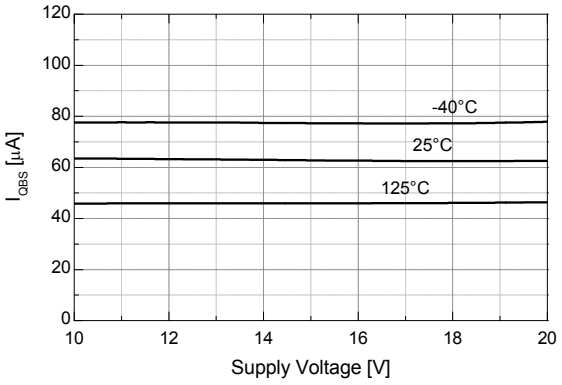

Figure 21. Quiescent V_{BS} Supply Current vs. Supply Voltage

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Switching Time Definitions

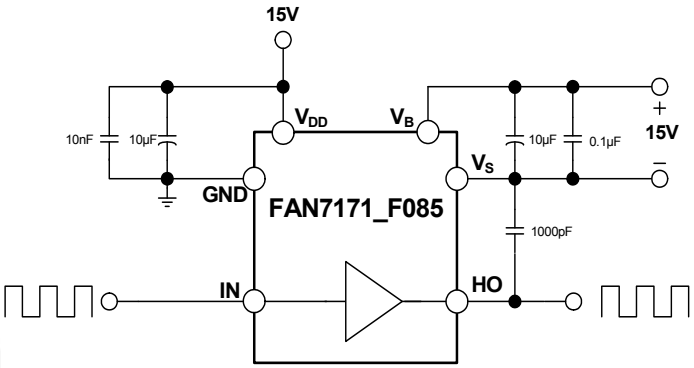

Figure 22. Switching Time Test Circuit (Referenced 8-SOP)

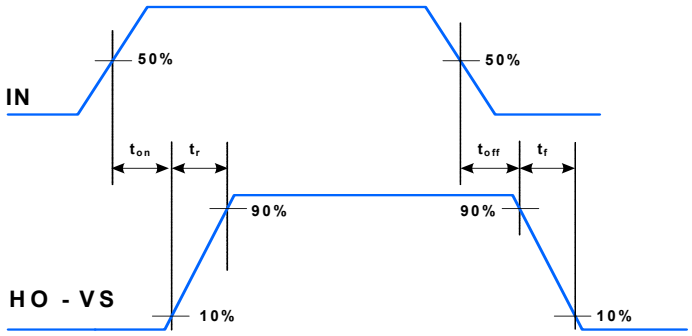

Figure 23. Switching Time Waveform Definitions

Physical Dimensions

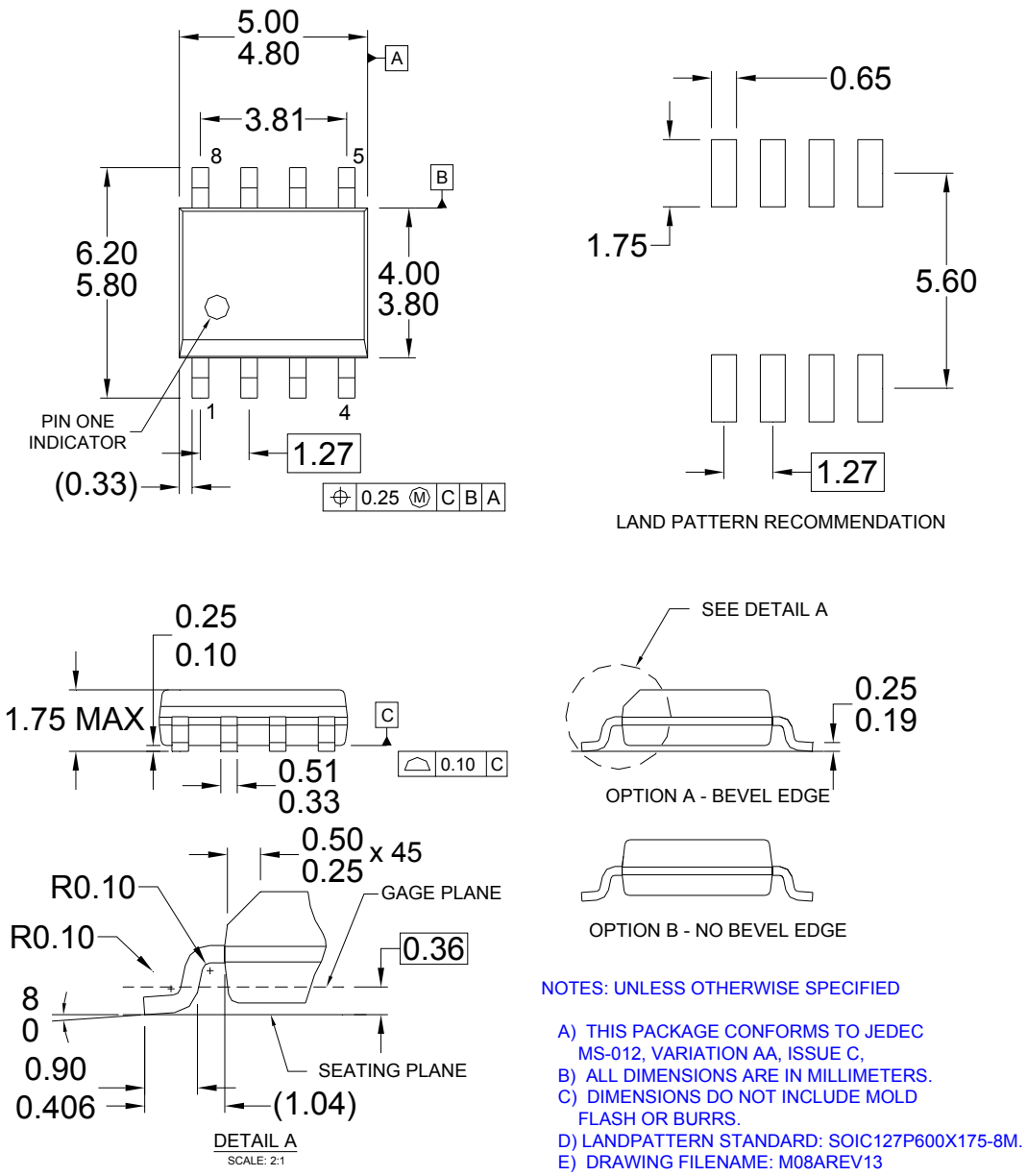

Figure 24. 8-Lead Small Outline Package (SOP)

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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